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April 1st, 2010 Renesas Electronics Corporation

Issued by: Renesas Electronics Corporation (http://www.renesas.com)

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BIPOLAR ANALOG INTEGRATED CIRCUIT $\mu PC4072$

J-FET INPUT LOW-NOISE DUAL OPERATIONAL AMPLIFIER

DESCRIPTION

The μ PC4072 is a J-FET input operational amplifier. This product is designed as low noise version of the μ PC4082. The features of the μ PC4072 are more improved input equivalent noise voltage, input offset voltage and input bias current than those of μ PC4082. By these features, the μ PC4072 is excellent choice for wide variety of applications including audio preamplifier and active filter.

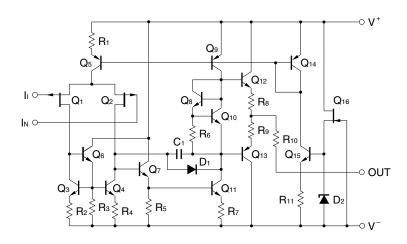
FEATURES

- Low noise: $e_n = 17 \text{ nV}/\sqrt{\text{Hz}} \text{ (TYP.)}$
- · Very low input bias and offset currents
- · Output short circuit protection
- High input impedance...J-FET Input stage
- Internal frequency compensation
- High slew rate...13 V/μs (TYP.)

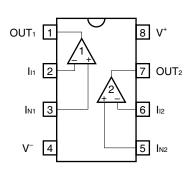
<R> ORDERING INFORMATION

| Part Number | Package |
|----------------|-----------------------------------|
| μPC4072C | 8-pin plastic DIP (7.62 mm (300)) |
| μ PC4072G2 | 8-pin plastic SOP (5.72 mm (225)) |

EQUIVALENT CIRCUIT (1/2 Circuit)



<R> PIN CONFIGURATION (Top View) μ PC4072C, 4072G2



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<R> ABSOLUTE MAXIMUM RATINGS (TA = 25°C)

| Par | ameter | Symbol | Ratings | Unit |
|----------------------------------|------------------------|------------------|--------------------------------|------|
| Voltage between V [⁺] a | nd V ^{-Note1} | $V^+ - V^-$ | -0.3 to +36 | ٧ |
| Differential Input Volta | age | VID | ±30 | ٧ |
| Input Voltage Note2 | | Vı | V^{-} – 0.3 to V^{+} + 0.3 | ٧ |
| Output Voltage Note3 | | Vo | V^{-} – 0.3 to V^{+} + 0.3 | ٧ |
| Power Dissipation | C Package Note4 | Рт | 350 | mW |
| | G2 Package Note5 | | 440 | mW |
| Output Short Circuit D | ouration Note6 | ts | Indefinite | sec |
| Operating Ambient Te | emperature | TA | -20 to +80 | °C |
| Storage Temperature | | T _{stg} | -55 to +125 | °C |

- **Notes 1.** Reverse connection of supply voltage can cause destruction.
 - 2. The input voltage should be allowed to input without damage or destruction. Even during the transition period of supply voltage, power on/off etc., this specification should be kept. The normal operation will establish when the both inputs are within the Common Mode Input Voltage Range of electrical characteristics.
 - 3. This specification is the voltage which should be allowed to supply to the output terminal from external without damage or destructive. Even during the transition period of supply voltage, power on/off etc., this specification should be kept. The output voltage of normal operation will be the Output Voltage Swing of electrical characteristics.
 - 4. Thermal derating factor is -5.0 mV/°C when operating ambient temperature is higher than 55°C.
 - 5. Thermal derating factor is -4.4 mV/°C when operating ambient temperature is higher than 25°C.
 - **6.** Pay careful attention to the total power dissipation not to exceed the absolute maximum ratings, Note 4 and Note 5.

RECOMMENDED OPERATING CONDITIONS

| Parameter | Symbol | MIN. | TYP. | MAX. | Unit |
|---|-----------------------|------|------|------|------|
| Supply Voltage | V [±] | ±5 | | ±16 | V |
| Output Current | lo | | | ±10 | mA |
| Capacitive Load (Av = +1, Rf = 0 Ω) | CL | | | 100 | pF |



ELECTRICAL CHARACTERISTICS (T_A = 25°C, V[±] = ± 15 V)

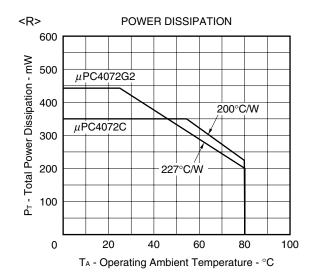
| Parameter | Symbol | Conditions | MIN. | TYP. | MAX. | Unit |
|---|------------|--|-------|--------|------|--------------------|
| Input Offset Voltage | Vio | Rs ≤ 50 Ω | | ±3 | ±10 | mV |
| Input Offset Current Note7 | lio | | | ±5 | ±50 | pA |
| Input Bias Current Note7 | Ів | | | 30 | 200 | pA |
| Large Signal Voltage Gain | Av | $R_L \ge 2 \ k\Omega$, $V_0 = \pm 10 \ V$ | 25000 | 200000 | | |
| Supply Current Note8 | Icc | lo = 0 A | | 4 | 5 | mA |
| Common Mode Rejection Ratio | CMR | | 70 | 86 | | dB |
| Supply Voltage Rejection Ratio | SVR | | 70 | 86 | | dB |
| Output Voltage Swing | Vom | R _L ≥ 10 kΩ | ±12 | ±13.5 | | ٧ |
| | | $R_L \ge 2 k\Omega$ | ±10 | ±12 | | ٧ |
| Common Model Input Voltage Range | VICM | | ±10 | | | V |
| Slew Rate | SR | Av = +1 | | 13 | | V/μs |
| Unity Gain Frequency | funity | | | 3 | | MHz |
| Input Equivalent Noise Voltage | Vn | Rs = 100 Ω , f = 10 Hz to 10 kHz | | 4 | | $\mu V_{r.m.s.}$ |
| Input Equivalent Noise Voltage Density | e n | Rs = 100 Ω, f = 1 kHz | | 17 | | nV/√ Hz |
| Channel Separation | | | | 120 | | dB |
| Input Offset Voltage | Vio | Rs \leq 50 Ω , TA = -20 to $+70$ °C | | | ±13 | mV |
| Average V _{IO} Temperature Drift | ΔV10/ΔΤ | T _A = -20 to +70°C | | ±10 | | μV/°C |
| Input Offset Current Note7 | lio | T _A = -20 to +70°C | | | ±2 | nA |
| Input Bias Current Note7 | Ів | T _A = -20 to +70°C | | | 7 | nA |

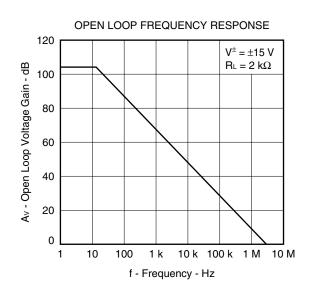
Notes 7. Input bias currents flow into IC. Because each currents are gate leak current of P-channel J-FET on input stage. And that are temperature sensitive. Short time measuring method is recommendable to maintain the junction temperature close to the operating ambient temperature.

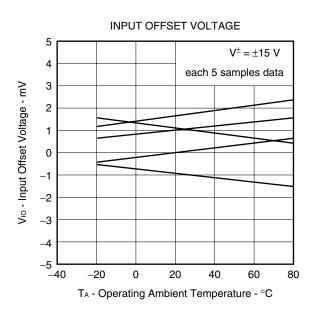
8. This current flows irrespective of the existence of use.

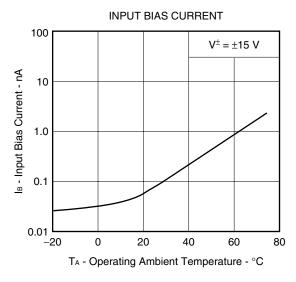


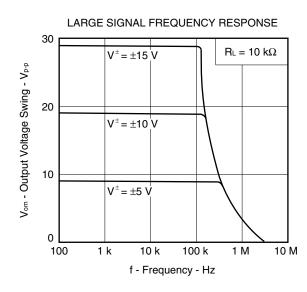
TYPICAL PERFORMANCE CHARACTERISTICS (TA = 25°C, TYP.)

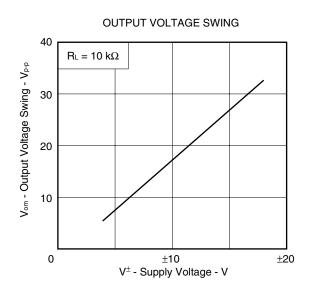


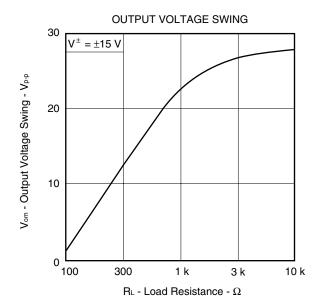


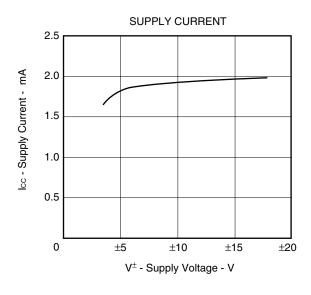


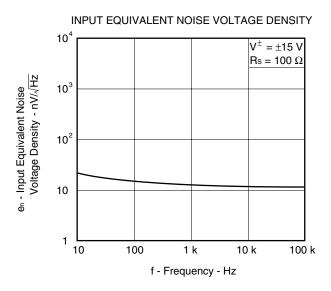


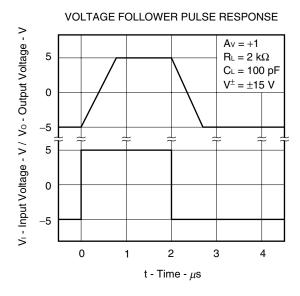






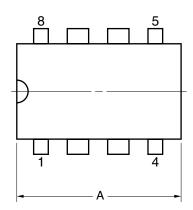


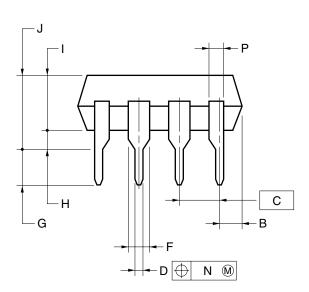


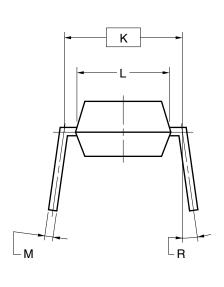


<R> PACKAGE DRAWINGS (Unit : mm)

8-PIN PLASTIC DIP (7.62mm(300))







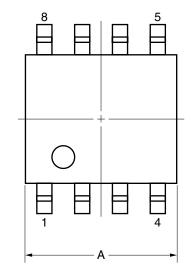
NOTES

- 1. Each lead centerline is located within 0.25 mm of its true position (T.P.) at maximum material condition.
- 2. Item "K" to center of leads when formed parallel.

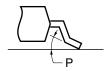
| ITEM | MILLIMETERS |
|------|------------------------|
| Α | 10.16 MAX. |
| В | 1.27 MAX. |
| С | 2.54 (T.P.) |
| D | 0.50±0.10 |
| F | 1.4 MIN. |
| G | 3.2±0.3 |
| Н | 0.51 MIN. |
| - 1 | 4.31 MAX. |
| J | 5.08 MAX. |
| K | 7.62 (T.P.) |
| L | 6.4 |
| М | $0.25^{+0.10}_{-0.05}$ |
| N | 0.25 |
| Р | 0.9 MIN. |
| R | 0~15° |
| | |

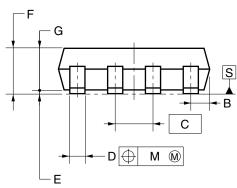
P8C-100-300B,C-2

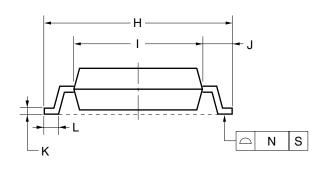
8-PIN PLASTIC SOP (5.72 mm (225))



detail of lead end







NOTE

Each lead centerline is located within 0.12 mm of its true position (T.P.) at maximum material condition.

| ITEM | MILLIMETERS |
|------|------------------------|
| Α | $5.2_{-0.20}^{+0.17}$ |
| В | 0.78 MAX. |
| С | 1.27 (T.P.) |
| D | $0.42^{+0.08}_{-0.07}$ |
| E | 0.1±0.1 |
| F | 1.59±0.21 |
| G | 1.49 |
| Н | 6.5±0.3 |
| ı | 4.4±0.15 |
| J | 1.1±0.2 |
| K | $0.17^{+0.08}_{-0.07}$ |
| L | 0.6±0.2 |
| М | 0.12 |
| N | 0.10 |
| Р | 3°+7° |
| | COOM EO OOED O |

S8GM-50-225B-6



<R> RECOMMENDED SOLDERING CONDITIONS

The μ PC4072 should be soldered and mounted under the following recommended conditions.

For soldering methods and conditions other than those recommended below, contact an NEC Electronics sales representative.

For technical information, see the following website.

Semiconductor Device Mount Manual (http://www.necel.com/pkg/en/mount/index.html)

Type of Surface Mount Device

μ PC4072G2: 8-pin plastic SOP (5.72 mm (225))

| Process | Conditions | Symbol |
|------------------------|---|-----------|
| Infrared Ray Reflow | Peak temperature: 230°C or below (Package surface temperature), Reflow time: 30 seconds or less (at 210°C or higher), Maximum number of reflow processes: 1 time. | IR30-00-1 |
| Vapor Phase Soldering | Peak temperature: 215°C or below (Package surface temperature), Reflow time: 40 seconds or less (at 200°C or higher), Maximum number of reflow processes: 1 time. | VP15-00-1 |
| Wave Soldering | Solder temperature: 260°C or below, Flow time: 10 seconds or less, Maximum number of flow processes: 1 time, Pre-heating temperature: 120°C or below (Package surface temperature). | WS60-00-1 |
| Partial Heating Method | Pin temperature: 300°C or below, Heat time: 3 seconds or less (Per each side of the device). | - |

Caution Apply only one kind of soldering condition to a device, except for "partial heating method", or the device will be damaged by heat stress.

Type of Through-hole Device

μ PC4072C: 8-pin plastic DIP (7.62 mm (300))

| Process | Conditions | | |
|------------------------|--|--|--|
| Wave Soldering | Solder temperature: 260°C or below, | | |
| (only to leads) | Flow time: 10 seconds or less. | | |
| Partial Heating Method | Pin temperature: 300°C or below, Heat time: 3 seconds or less (per each lead). | | |

Caution For through-hole device, the wave soldering process must be applied only to leads, and make sure that the package body does not get jet soldered.

<R> REFERENCE DOCUMENTS

QUALITY GRADES ON NEC SEMICONDUCTOR DEVICES
SEMICONDUCTOR DEVICE MOUNT MANUAL
NEC SEMICONDUCTOR DEVICE RELIABILITY/
QUALITY CONTROL SYSTEM- STANDARD LINEAR IC

C11531E

http://www.necel.com/pkg/en/mount/index.html

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